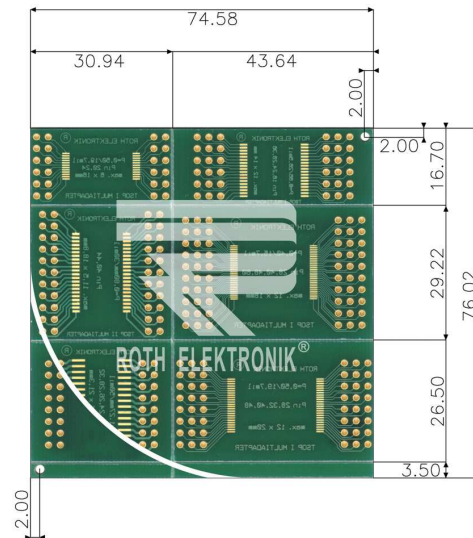




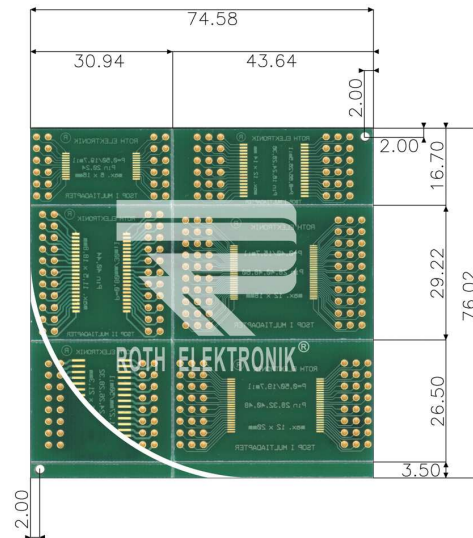
## RE900

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for 14 different SMD TSOP I and 7 different SMD TSOP II chips
- Pitch 0.40 mm (15.7 mil); 0.50 mm (19.7 mil); 0.65 mm (26.5 mil); 0.80 mm (30 mil); 1.27 mm (50 mil)
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual moduls from the board
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size: 72.60 x 76.20 mm

Modul-No. Type Pitch Pin Size (mm)

RE900-01 TSOP I 0.400 mm 28, 40, 48, 60 12.00 x 18.00 RE900-02 TSOP I 0.500 mm 28, 32, 40, 48 12.00 x 20.00 RE900-03 TSOP I 0.500 mm 20, 24 6.00 x 16.00 RE900-04 TSOP I 0.650 mm 16, 24, 28, 36 12.00 x 14.00 RE900-05 TSOP II 0.800 mm 40, 44 11.50 x 18.80 RE900-06 TSOP II 1.270 mm 20, 24, 26, 28, 32 11.50 x 21.30

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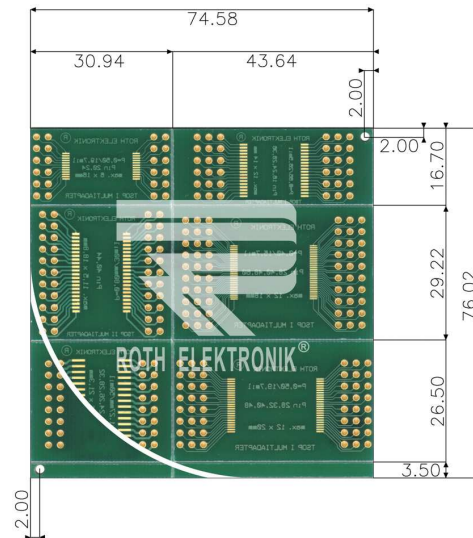


## RE900

- Epoxydglashartgewebe FR4 1,50 mm
- Zweiseitig 35 µm Cu
- Durchkontaktiert (PTH)
- Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
- Adaptionssplattine für 14 verschiedene SMD TSOP I und 7 verschiedene SMD TSOP II
- Pitch 0,40 mm (15.7 mil); 0,50 mm (19.7 mil); 0,65 mm (26.5 mil); 0,80 mm (30 mil); 1,27 mm (50 mil)
- Lochdurchmesser 1,00 mm
- Vorgeritzte Sollbruchstellen zum Trennen einzelner Module von der Platine
- Gerberdaten zur Herstellung des Lötpastenaufdrucks werden auf Anfrage zur Verfügung gestellt
- Größe 72,60 x 76,20 mm

Modul-Nr. Typ Pitch Pin Größe (mm)

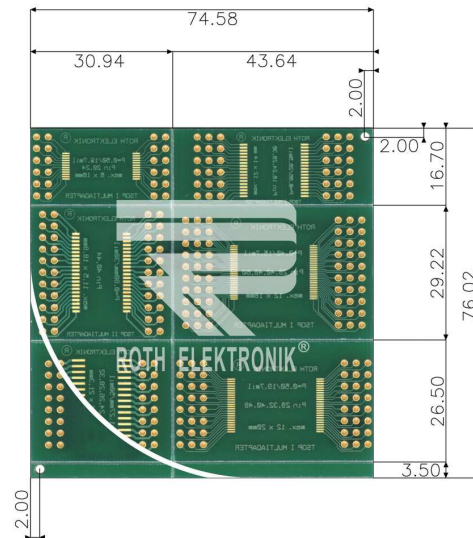
RE900-01 TSOP I 0,400 mm 28, 40, 48, 60 12,00 x 18,00 RE900-02 TSOP I 0,500 mm 28, 32, 40, 48 12,00 x 20,00 RE900-03 TSOP I 0,500 mm 20, 24 6,00 x 16,00 RE900-04 TSOP I 0,650 mm 16, 24, 28, 36 12,00 x 14,00 RE900-05 TSOP II 0,800 mm 40, 44 11,50 x 18,80 RE900-06 TSOP II 1,270 mm 20, 24, 26, 28, 32 11,50 x 21,30



## RE900

- Fibre de verre FR4 époxyde 1,50 mm
  - Double face 35 µm Cu
  - Métallisation des trous (PTH)
  - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
  - Platine d'adaptation pour 14 chips CMS TSOP I et 7 chips CMS TSOP II différents
  - Pitch 0,40 mm (15.7 mil); 0,50 mm (19.7 mil); 0,65 mm (26.5 mil); 0,80 mm (30 mil); 1,27 mm (50 mil)
  - Perforation 1,00 mm Ø
  - Points destinés à la rupture pour séparer des modules de la platine
  - Les données Data Gerber d'apprêt pour l'établissement de l'application de pâte à braser seront mis à la disposition gratuitement
  - Dimensions: 72,60 x 76,20 mm
- Module-No. Type Pitch Pin Dimensions (mm)

RE900-01 TSOP I 0,400 mm 28, 40, 48, 60 12,00 x 18,00 RE900-02 TSOP I 0,500 mm 28, 32, 40, 48 12,00 x 20,00 RE900-03 TSOP I 0,500 mm 20, 24 6,00 x 16,00 RE900-04 TSOP I 0,650 mm 16, 24, 28, 36 12,00 x 14,00 RE900-05 TSOP II 0,800 mm 40, 44 11,50 x 18,80 RE900-06 TSOP II 1,270 mm 20, 24, 26, 28, 32 11,50 x 21,30



## RE900

- Fibra de vidrio epoxídica FR4 1,50 mm
- Por dos lados 35 µm de Cu
- Agujeros con contactos metalizados PTH)
- Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
- Placa de circuito impreso de adaptación para 14 SMD TSOP I y 7 diferentes SMD TSOP II chips
- Distancia entre las zonas terminales 0,40 mm (15.7 mil); 0,50 mm (19.7 mil); 0,65 mm (26.5 mil); 0,80 mm (30 mil); 1,27 mm (50 mil)
- Diámetro de agujeros 1,00 mm
- Puntos de ruptura controlada prerrayados para separar módulo individuales de la placa de circuito impreso
- Bajo demanda se ponen a disposición gratuitamente los datos Gerber para la fabricación de la impresión de pasta de soldar
- Tamaño 72,60 x 76,20 mm

Módulo-No. Typ Pitch Pin Tamaño (mm)

RE900-01 TSOP I 0,400 mm 28, 40, 48, 60 12,00 x 18,00 RE900-02 TSOP I 0,500 mm 28, 32, 40, 48 12,00 x 20,00 RE900-03 TSOP I 0,500 mm 20, 24 6,00 x 16,00 RE900-04 TSOP I 0,650 mm 16, 24, 28, 36 12,00 x 14,00 RE900-05 TSOP II 0,800 mm 40, 44 11,50 x 18,80 RE900-06 TSOP II 1,270 mm 20, 24, 26, 28, 32 11,50 x 21,30

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